

FORM PTO-1595

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(Rev. 6-93) OMB No. 0651-0011 (exp. 4/94)

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): Siemens Dematic Electronics Assembly Systems, Inc. Additional name(s) of conveying party(ies) attached? \_\_\_ Yes X No

2. Name and address of receiving party(ies) Name: Siemens Dematic Aktiengesellschaft Internal Address: Street Address: Werner-von-Siemens- Str. 9 76646 Bruchsal, Germany City: State: ZIP: Additional name(s) & address(es) attached? \_\_\_ Yes X No

3. Nature of conveyance: X Assignment \_\_\_ Merger \_\_\_ Security Agreement \_\_\_ Change of Name \_\_\_ Other Execution Date: June 14, 2002

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) 10/112,849; 10/077,725; 10/077,728; 10/085,224; 10/035,692; 10/052,428; 10/052,399; 60/358,771; 60/367,613; 60/370,593; 10/120,029

B. Patent No.(s) Additional numbers attached? \_\_\_ Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Elsa Keller Internal Address: Siemens Corporation Intellectual Property Department Street Address: 186 Wood Avenue South City: Iselin State: NJ ZIP: 08830

6. Total number of applications and patents involved: eleven 7. Total Fee (37 CFR 3.41) \$ 440.00 \_\_\_ Enclosed X Authorized to be charged to deposit account 8. Deposit Account No. 19-2179

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9. Statement and signature To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Frank J. Nuzzi, Esq. Reg. No.: 42,944 Name of Person Signing Signature Date 6/28/02 Total number of pages including cover sheet, attachments, and document: 3

## ASSIGNMENT

WHEREAS, Siemens Dematic Electronics Assembly Systems, Inc., ("SDEAS") is the owner of the entire rights, title and interest in and to the invention described in the following inventions and patent applications:

### INVENTIONS

IPD Docket No.	Disclosure Date	Title of Invention Disclosure	Inventors
2002E03080 US	02.22.2002	High Compliance Polymer Stud Grid Array	Higgins III, Leo M.;
2002E05211 US	03.26.2002	Laser Structured and Injection Molded Polymer Stud Grid Array (PSGA tm) Technology for Optoelectronics	Higgins III, Leo M.;
2001E21151 US	11.05.2001	Minimization of Thermal Loading	Hofmann, Neal;Schreiner, Alex F.;

### PATENT APPLICATIONS

Internal File Ref.	Filing Date	Title Of Patent Application	Appl. Type
2001P05738 US01	03.29.2002	Method and Structure for Ex-Situ Wafer Scale Polymer Stud Grid Array Contact Formation	Standard
2001P05738 WO	04.01.2002	Method and Structure for Ex-Situ Polymer Stud Grid Array Contact Formation	Standard
2001P07479 TW	02.15.2002	Method And System For Automated Dynamic Fiberoptic Alignment and Assembly	Standard
2001P07479 US01	02.15.2002	Method And System For Automated Dynamic Fiber optic Alignment and Assembly	Standard
2001P07479 WO	02.19.2002	Method And System For Automated Dynamic Fiberoptic Alignment and Assembly	Standard
2001P07480 TW	02.15.2002	High Strength Vias	Standard
2001P07480 US01	02.15.2002	High Strength Vias	Standard
2001P07480 WO	02.19.2002	High Strength Vias	Standard
2001P07506 TW	03.01.2002	Method And Structure Of In-Situ Wafer Scale Polymer Stud Grid Array Contact Formation	Standard
2001P07506 US01	02.28.2002	Method And Structure Of In-Situ Wafer Scale Polymer Stud Grid Array Contact Formation	Standard

PATENT APPLICATIONS, continued

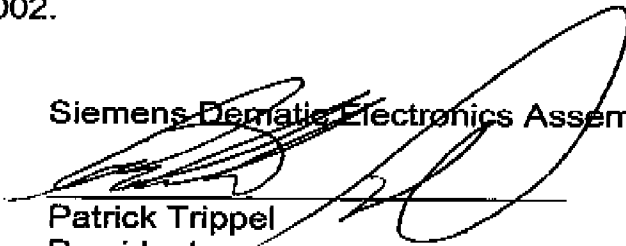
2001P07506	WO	03.01.2002	Method And Structure Of In-Situ Wafer Scale Polymer Stud Grid Array Contact Formation	Standard
2001P17776	US01	11.07.2001	Laser System by Modulation of Power and Energy	Standard
2002P00898	US	01.18.2002	Defective Circuit Scanning Device and Method	Divisional
2002P00899	US	01.18.2002	Defective Circuit Scanning Device and Method	Divisional
2002P03083	US	02.22.2002	High Compliance Polymer Stud Grid Array	Provisional
2002P05215	US	03.26.2002	Laser Structured and Injection Molded Polymer Stud Grid Array (PSGA tm) Technology for Optoelectronics	Provisional
2002P05649	US	04.04.2002	Method of Laser Machining Materials with Minimal Thermal Loading by Using Isolation Cuts	Provisional
2002P05651	US	04.10.2002	Method of Laser Machining Materials with Minimal Thermal Loading	Standard

AND WHEREAS, Siemens Dematic Aktiengesellschaft, Business Unit SD EA 4, Bruchsal, Germany ("SD EA 4") is desirous of acquiring all right, title and interest in the United States in and to the aforesaid inventions and patent applications.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the aforesaid SDEAS does hereby sell and assign to the aforesaid SD EA 4 all its rights, title and interest in and to the above mentioned United States patent.

IN TESTIMONY WHEREOF, the undersigned has herewith caused this Assignment to be executed by its duly authorized officer this 14 day of JUNE, 2002.

Siemens Dematic Electronics Assembly Systems, Inc.

  
Patrick Trippel  
President

On this 14th day of June, 2002, before me personally appeared Patrick Trippel, proved to me on the basis of satisfactory evidence to be the person who executed the above Assignment as Vice President on behalf of Siemens Corporation and acknowledged to me that the corporation executed it. WITNESS my hand and official seal.

State of Georgia )  
County of )

Notary Public, Gwinnett County, Georgia  
My Commission Expires October 7, 2005

  
Notary Public

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